

Title (en)

MEASURING THE EFFECT OF FLARE ON LINE WIDTH

Title (de)

MESSUNG DES FLARE-EFFEKTES AUF DIE LINIENBREITE

Title (fr)

MESURE DE L'EFFET DE LA LUMIERE PARASITE SUR LA LARGEUR DES PISTES CONDUCTRICES

Publication

**EP 1654592 A2 20060510 (EN)**

Application

**EP 04744097 A 20040731**

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Abstract (en)

[origin: WO2005013004A2] In photo-lithography, one may assess the effect of flare due to various exposure tools. In an example embodiment, in a photo-lithography process on a photo resist coated substrate, there is a method (600) for determining the effect of flare on line shortening. The method (600) comprises, at a first die position on the substrate and in a first exposure, printing a first mask (610) that includes a flare pattern corresponding to one corner of the first mask (610), and in a second exposure, printing a second mask (620) that includes another flare pattern corresponding to an opposite corner of the second mask. At a second die position on the substrate, a composite mask pattern (630) based on features of the first mask and the second is printed. The printed patterns (640) are developed and measurements (650) are obtained therefrom. The effect of flare (660) is determined as a function of the measurements.

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